

DESCRIPTION

The ICPLM452 and ICPLM453 devices each consists of an infrared emitting diode optically coupled to a high speed integrated photo detector. A separate connection of the photodiode bias and output transistor collector increases the speed by several orders of magnitude over conventional phototransistor couplers by reducing the base-collector capacitance.

These devices belong to Isocom Compact Range of optocouplers.

- 1. Anode
- 3. Cathode
- 4. GND
- 5. Vout
- 6. Vcc

FEATURES

- High speed 1Mbit/s
- Half Pitch 1.27mm
- Common Mode Transient Immunity 15kV/µs min (ICPLM453)
- High AC Isolation Voltage 3750V_{RMS}
- Guaranteed Performance from 0°C to 70°C
- Operating Temperature Range from -40°C to 85°C
- Pb Free and RoHS Compliant
- Safety Approvals Pending

APPLICATIONS

- Line Receivers
- Field Bus Communication and Control
- Power Transformer Isolation in Motor Drives
- Replacement for Low Speed phototransistor Couplers
- High Speed Logic Ground isolation
- Analog Signal Ground Isolation

ORDER INFORMATION

 Available in Tape and Reel with 3000pcs per reel.

ABSOLUTE MAXIMUM RATINGS $(T_A = 25^{\circ}C)$

Input Diode

Forward Current 2	25mA
Peak Forward Current 5	60mA
(50% Duty Cycle, 1ms P.W)	
Peak Transient Current	1A
(≤ 1µs P.W., 300pps)	
Reverse Voltage 5	δV
Power dissipation 4	5mW

Output

Output Current	8mA
Peak Output Current	16mA
Output Voltage	-0.5 to 20V
Supply Voltage	-0.5 to 30V
Power Dissipation	100mW

Total Package

Isolation Voltage	$3750V_{RMS}$
Operating Temperature	-40 to 85 °C
Storage Temperature	-55 to 125 °C
Lead Soldering Temperature (10s)	260°C

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ELECTRICAL CHARACTERISTICS ($T_A = 0$ °C to 70°C unless otherwise specified)

INPUT

Parameter	Symbol	Test Condition	Min	Тур.*	Max	Unit
Forward Voltage	V_{F}	$I_F = 16\text{mA}$		1.45	1.8	V
Reverse Voltage	V_R	$I_R = 10 \mu A, T_A = 25 ^{\circ} C$	5.0			V
Temperature Coefficient of V_F	$\Delta V_F/\Delta T_A$	$I_F = 16mA$		-1.6		mV/°C

OUTPUT

Parameter	Symbol	Test Condition	Min	Typ.*	Max	Unit
High Level Supply Current	I_{CCH}	$I_F = 0$ mA, $V_O = O$ pen, $V_{CC} = 15$ V, $T_A = 25$ °C		0.05	1	μΑ
		$I_F = 0$ mA, $V_O = O$ pen, $V_{CC} = 15V$			2	
Low Level Supply Current	I_{CCL}	$I_F = 16\text{mA}, V_O = \text{Open},$ $V_{CC} = 15\text{V}$		100	200	μΑ

COUPLED

Parameter	Symbol	Test Condition	Min	Тур.*	Max	Unit
Current Transfer Ratio	CTR	$I_F = 16mA, V_O = 0.4V,$ $V_{CC} = 4.5V, T_A = 25^{\circ}C$	20		50	%
		$I_F = 16\text{mA}, V_O = 0.5\text{V}, \ V_{CC} = 4.5\text{V}$	15			
High Level Output Current	I_{OH}	$I_F = 0$ mA, $V_O = V_{CC} = 5.5$ V, $T_A = 25$ °C		0.001	0.5	μΑ
		$I_F = 0 \text{mA}, V_O = V_{CC} = 15 \text{V},$ $T_A = 25 ^{\circ}\text{C}$		0.001	1	
		$I_F = 0 \text{mA}, V_O = V_{CC} = 15 \text{V}$			50	
Low Level Output Voltage	$V_{ m OL}$	$I_F = 16\text{mA}, I_O = 3\text{mA},$ $V_{CC} = 4.5\text{V}, T_A = 25^{\circ}\text{C}$			0.4	V
		$I_F = 16mA, I_O = 2.4mA,$ $V_{CC} = 4.5V$			0.5	

^{*} Typical values at $T_A = 25$ °C



ELECTRICAL CHARACTERISTICS (T_A = 0°C to 70°C unless otherwise specified)

Switching Characteristics (V_{cc} = 5V unless otherwise specified)

Parameter	Symbol	Test Condition	Min	Тур.*	Max	Unit
Propagation Delay Time to Logic Low	$T_{ m PHL}$	$I_F = 16\text{mA}, \ R_L = 1.9\text{k}\Omega,$ $T_A = 25^{\circ}\text{C}$		0.4	0.8	μs
		$I_F = 16\text{mA}, \ R_L = 1.9\text{k}\Omega,$			1.0	
Propagation Delay Time to Logic High	$T_{ m PLH}$	$I_F = 16\text{mA}, \ R_L = 1.9\text{k}\Omega,$ $T_A = 25^{\circ}\text{C}$		0.35	0.8	μs
		$I_F = 16\text{mA}, \ R_L = 1.9\text{k}\Omega,$			1.0	ns
Common Mode Transient Immunity at Logic High	CM _H	$ICPLM452$ $I_F = 0mA, R_L = 1.9k\Omega,$ $V_{CM} = 10Vp-p, T_A = 25^{\circ}C$	5000			V/µs
		ICPLM453 $I_F = 0 \text{mA}, R_L = 1.9 \text{k}\Omega,$ $V_{CM} = 1500 \text{Vp-p}, T_A = 25 ^{\circ}\text{C}$	15000			
Common Mode Transient Immunity at Logic Low	CM_L	ICPLM452 $I_F = 16\text{mA}, R_L = 1.9\text{k}\Omega, \\ V_{CM} = 10\text{Vp-p}, T_A = 25^{\circ}\text{C}$	5000			V/μs
		ICPLM453 $I_F = 16 \text{mA}, R_L = 1.9 \text{k}\Omega, \\ V_{CM} = 1500 \text{Vp-p}, T_A = 25 ^{\circ}\text{C}$	15000			

^{*} Typical values at $T_A = 25$ °C

 CM_L – The maximum tolerable rate of fall of the common mode voltage to dV_{CM}/t , to ensure the output will remain in the LOW output state (i.e., V_{OUT} < 0.8V).

 CM_H – The maximum tolerable rate of rise of the common mode voltage dV_{CM}/t , to ensure the output will remain in the HIGH state (i.e., $V_{OUT} > 2.0V$).



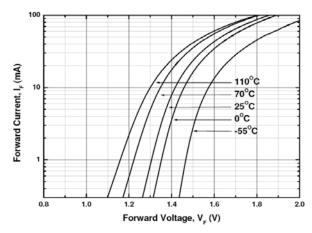


Fig 1 Forward Current vs Forward Voltage

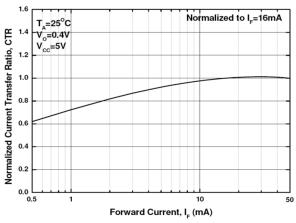


Fig 3 Normalized CTR vs Forward Current

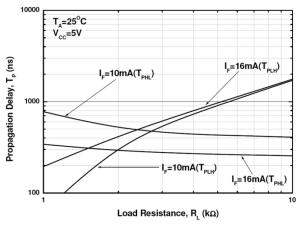


Fig 5 Propagation Delay vs Load Resistance

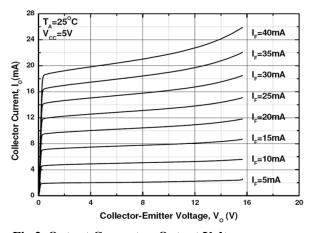


Fig 2 Output Current vs Output Voltage

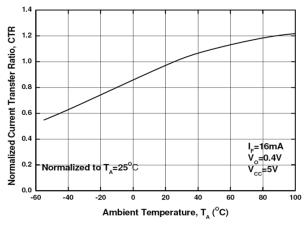


Fig 4 Normalized CTR vs T_A

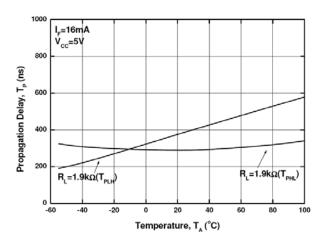


Fig 6 Propagation Delay vs T_A



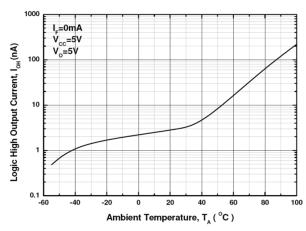


Fig 7 Logic High Output Current vs T_A

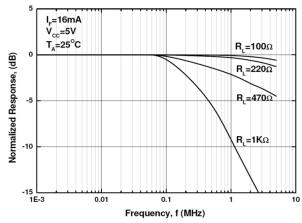


Fig 8 Frequency Response



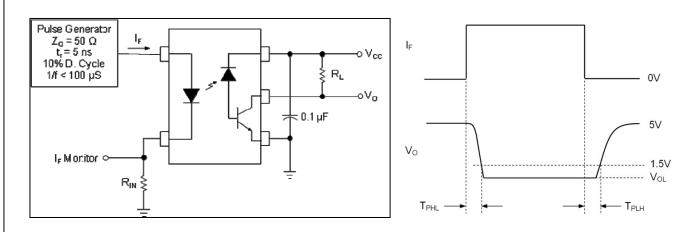


Fig 9 Switching Time Test Circuit

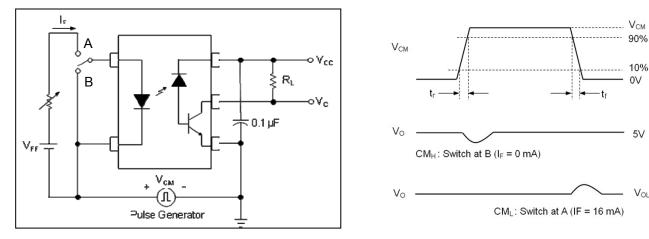


Fig 10 Common Mode Transient Immunity Test Circuit

Common mode transient immunity in logic high level is the maximum tolerable (positive) dV_{CM}/dt on the leading edge of the common mode pulse signal V_{CM} , to assure that the output will remain in a logic high state (i.e., $V_O > 2.0V$).

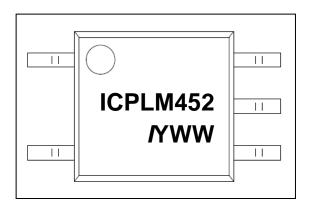
Common mode transient immunity in logic low level is the maximum tolerable (negative) dV_{CM}/dt on the trailing edge of the common mode pulse signal, V_{CM} , to assure that the output will remain in a logic low state (i.e., $V_O < 0.8V$).



ORDER INFORMATION

ICPLM452, ICPLM453					
After PN	fter PN PN Description Packing quantity				
None	ICPLM452, ICPLM453	Surface Mount Tape & Reel	3000 pcs per reel		

DEVICE MARKING



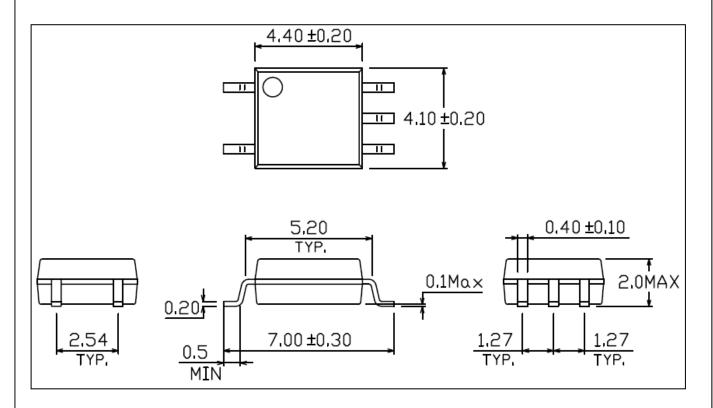
ICPLM600 denotes Device Part Number (ICPLM452 is used as example)

Y denotes 1 digit Year code WW denotes 2 digit Week code

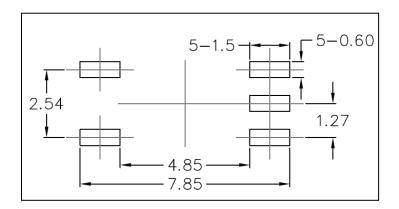
denotes Isocom



PACKAGE DIMENSIONS (mm)

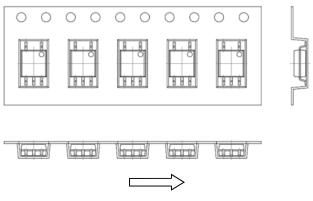


RECOMMENDED PAD LAYOUT (mm)

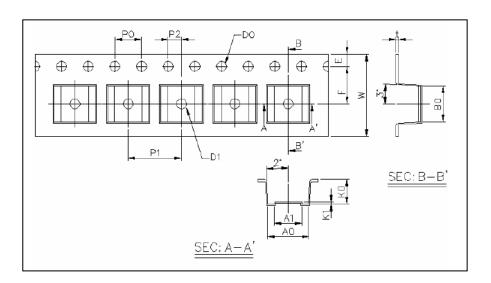




TAPE AND REEL PACKAGING



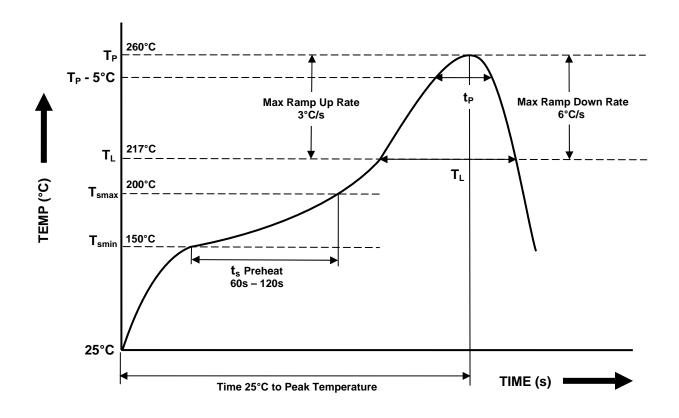
Direction of feed from reel



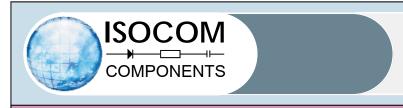
Dimension No.	Α0	A 1	В0	D0	D1	E	F
Dimension (mm)	6.2±0.1	4.1±0.1	5.28±0.1	1.5±0.1	1.5±0.3	1.75±0.1	5.5±0.1
Dimension No.	P0	P1	P2	t	w	K0	K0
Dimension (mm)	4.0±0.1	8.0±0.1	2.0±0.1	0.4±0.1	12.0 +0.3/-0.1	3.7±0.1	0.3±0.1



IR REFLOW SOLDERING TEMPERATURE PROFILE (One Time Reflow Soldering is Recommended)



Profile Details	Conditions
Preheat - Min Temperature (T _{SMIN}) - Max Temperature (T _{SMAX}) - Time T _{SMIN} to T _{SMAX} (t _s)	150°C 200°C 60s - 120s
	260°C 217°C 30s 60s - 100s 3°C/s max 6°C/s max
Average Ramp Up Rate (T _{smax} to T _P)	3°C/s max
Time 25°C to Peak Temperature	8 minutes max



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- When requiring a device for any "specific" application, please contact our sales for advice.
- The contents described herein are subject to change without prior notice.
- Do not immerse device body in solder paste.



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